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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Solid State Relay OCMOS FET

PS7122A-1A,-2A,PS7122AL-1A,-2A

6, 8-PIN DIP, 250 V BREAK DOWN VOLTAGE NORMALLY OPEN TYPE 1-ch, 2-ch Optical Coupled MOS FET

-NEPOC Series-

DESCRIPTION

The PS7122A-1A, -2A and PS7122AL-1A, -2A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7122AL-1A, -2A have a surface mount type lead.

FEATURES

- 1 channel type (1 a output) or 2 channel type (1 a + 1 a output)
- Low LED operating current (IF = 2 mA)
- Designed for AC/DC switching line changer
- Small package (6, 8-pin DIP)
- Low offset voltage
- Ordering number of taping product : PS7122AL-1A-E3, E4: 1 000 pcs/reel
 - : PS7122AL-2A-E3, E4: 1 000 pcs/reel

<R> • Pb-Free product

- Safety standards
 - UL approved: File No. E72422
 - BSI approved: No. 8245/8246
 - CSA approved: No. CA 101391

APPLICATIONS

- Exchange equipment
- Measurement equipment
- FA/OA equipment

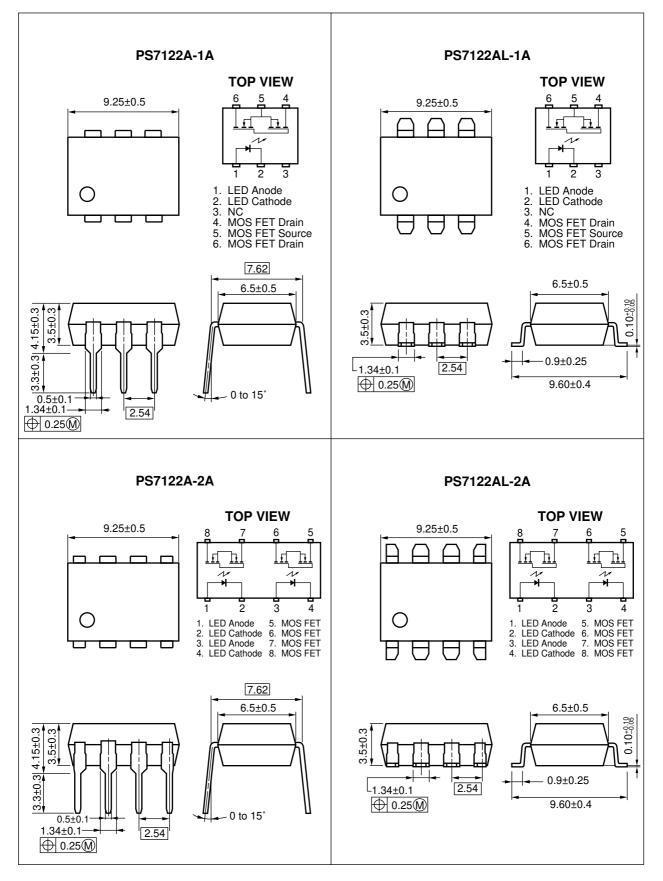
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The mark <R> shows major revised points.

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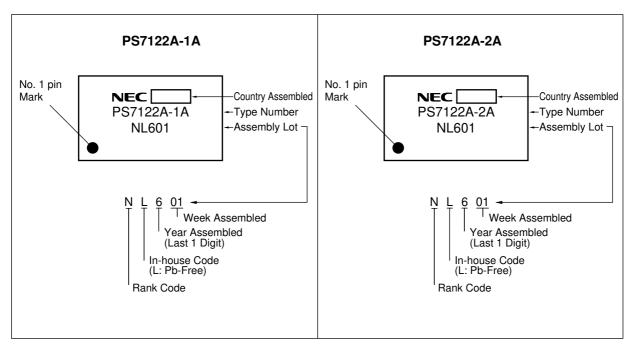
The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

PACKAGE DIMENSIONS (in millimeters)



Data Sheet PN10273EJ02V0DS

<R> MARKING EXAMPLE



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS7122A-1A	PS7122A-1A-A	Pb-Free	Magazine case 50 pcs	Standard products	PS7122A-1A
PS7122AL-1A	PS7122AL-1A-A			(UL, BSI, CSA	
PS7122AL-1A-E3	PS7122AL-1A-E3-A		Embossed Tape 1 000 pcs/reel	approved)	
PS7122AL-1A-E4	PS7122AL-1A-E4-A				
PS7122A-2A	PS7122A-2A-A		Magazine case 50 pcs		PS7122A-2A
PS7122AL-2A	PS7122AL-2A-A				
PS7122AL-2A-E3	PS7122AL-2A-E3-A		Embossed Tape 1 000 pcs/reel		
PS7122AL-2A-E4	PS7122AL-2A-E4-A				

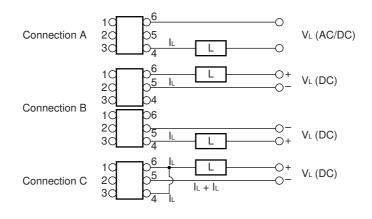
*1 For the application of the Safety Standard, following part number should be used.

				Ratings		
Parameter			Symbol	PS7122A-1A, PS7122AL-1A	PS7122A-2A, PS7122AL-2A	Unit
Diode	Forward Current (D	C)	lf	50		mA/ch
	Reverse Voltage		VR	5.0		V
	Power Dissipation		PD	50		mW/ch
	Peak Forward Current ¹¹		IFP	1		A/ch
MOS FET	DS FET Break Down Voltage		VL	250		V
	Continuous	Connection A	١L	20	00	mA/ch
	Load Current *2	Connection B		350	_	
		Connection C		500	_	
	Pulse Load Current ^{*3} (AC/DC Connection)		Ilp	400		mA/ch
Power Dissipation		PD	560	375	mW/ch	
Isolation Voltage ^{*4}			BV	1 500		Vr.m.s.
Total Power Dissipation			Рт	610	850	mW
Operating Ambient Temperature			Ta	-40 to +85		°C
Storage Temperature			Tstg	-40 to +100		°C

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

*1 PW = 100 µs, Duty Cycle = 1%

*2 Conditions: IF \geq 2 mA. The following types of load connections are available.



*3 PW = 100 ms, 1 shot

*4 AC voltage for 1 minute at $T_A = 25^{\circ}$ C, RH = 60% between input and output Pins 1-3 shorted together, 4-6 shorted together. (PS7122A-1A) Pins 1-4 shorted together, 5-8 shorted together. (PS7122A-2A)

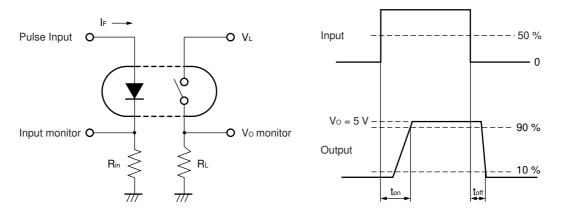
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	IR	$V_R = 5 V$			5.0	μA
MOS FET	Off-state Leakage Current	ILoff	V _D = 250 V		0.03	1.0	μA
	Output Capacitance	Cout	$V_D = 0 V, f = 1 MHz$		120		pF/ch
Coupled	LED On-state Current	lFon	l∟ = 200 mA			2.0	mA
	On-state Resistance	Ron1	I⊧ = 10 mA, I∟ = 10 mA		4.5	8.0	Ω
		Ron2	I_{F} = 10 mA, I_{L} = 200 mA, $t \leq$ 10 ms				
	Turn-on Time *1, 2	ton	IF = 10 mA, Vo = 5 V, RL = 500 Ω,		0.5	1.5	ms
	Turn-off Time *1, 2	toff	PW ≥ 10 ms		0.04	0.2	
	Isolation Resistance	R⊦o	VI-O = 1.0 kVDC	10 ⁹			Ω
	Isolation Capacitance	CI-O	V = 0 V, f = 1 MHz		1.1		pF/ch

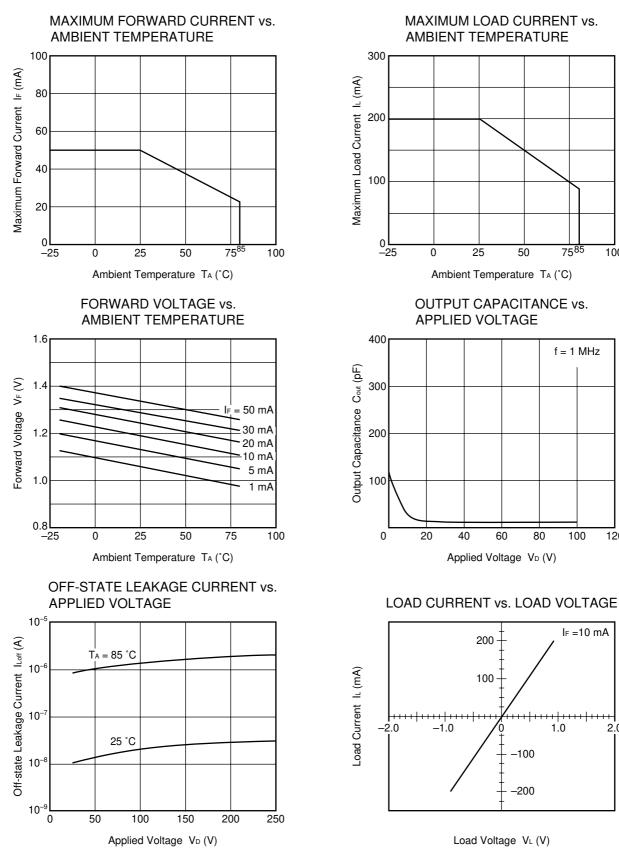
*1 Test Circuit for Switching Time



<R>

*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.
 Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

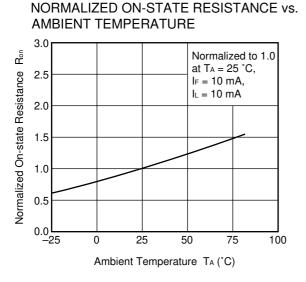


Remark The graphs indicate nominal characteristics.

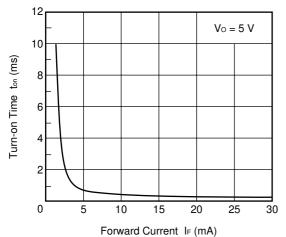
100

120

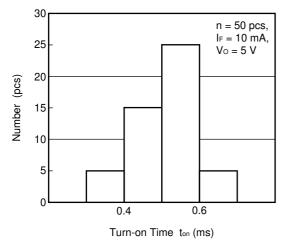
2.0



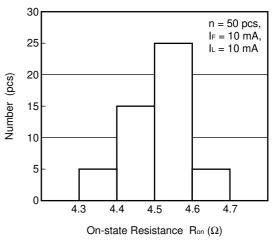
TURN-ON TIME vs. FORWARD CURRENT



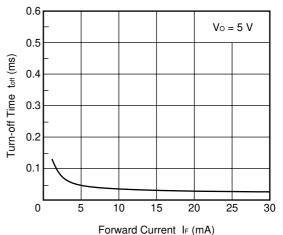
TURN-ON TIME DISTRIBUTION



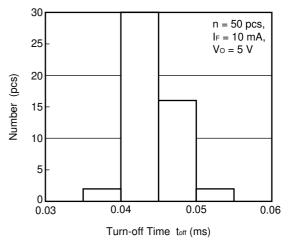
Remark The graphs indicate nominal characteristics.



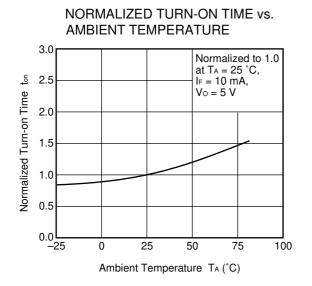
TURN-OFF TIME vs. FORWARD CURRENT



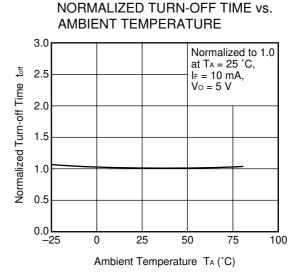
TURN-OFF TIME DISTRIBUTION



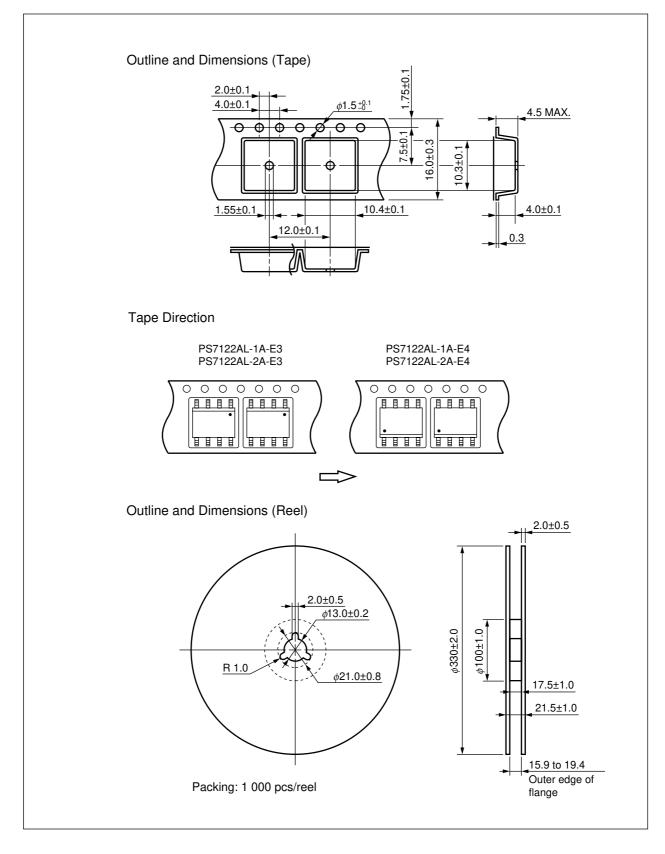
ON-STATE RESISTANCE DISTRIBUTION



Remark The graphs indicate nominal characteristics.



TAPING SPECIFICATIONS (in millimeters)

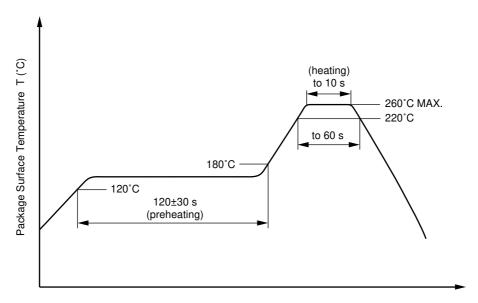


RECOMMENDED SOLDERING CONDITIONS

- (1) Infrared reflow soldering
 - Peak reflow temperature
 - Time of peak reflow temperature
 - Time of temperature higher than 220°C
 - Time to preheat temperature from 120 to 180°C
 - Number of reflows
 - Flux

260°C or below (package surface temperature) 10 seconds or less 60 seconds or less 120±30 s Three Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

 Temperature 	260°C or below (molten solder temperature)
---------------------------------	--

- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times
 One
- Flux

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

<R> (3) Soldering by soldering iron

350°C or below
3 seconds or less
Rosin flux containing small amount of chlorine (The flux with a
maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> USAGE CAUTIONS

- **1.** Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.
	 Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	 Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
	Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
	Do not burn, destroy, cut, crush, or chemically dissolve the product.
	Do not lick the product or in any way allow it to enter the mouth.

 NEC Compound Semiconductor Devices Hong Kong Limited

 E-mail: contact@ncsd-hk.necel.com

 Hong Kong Head Office
 TEL: +852-3107-7303

 Taipei Branch Office
 TEL: +886-2-8712-0478

 Korea Branch Office
 TEL: +82-2-558-2120

 NEC Electronics (Europe)
 GmbH

 http://www.eu.necel.com/

 TEL: +49-211-6503-0

 California Eastern Laboratories, Inc.
 http://www.cel.com/

 TEL: +1-408-988-3500
 FAX: +1-408-988-0279

Compound Semiconductor Devices Division NEC Electronics Corporation URL: http://www.ncsd.necel.com/

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